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APR-MAY

B. E. (Eighth Semester) Examination, 2020

(New Course)

(Electronics & Telecommunication Engg. Branch)

ENTERPRISE RESOURCE PLANNING

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Attempt all questions. Part (a) of each unit is compulsory carry 2 marks. Attempt any two parts from (b), (c) and (d) carry 7 marks. Assume suitable data if required.

Unit-I

1. (a) Define ERP.
- (b) What are the functional areas of business operations.

- (c) Define the roles and objectives of material management.
- (d) Briefly describe forecasting subsystem. Also explain some forecasting methods.

Unit-II

- 2. (a) Explain the term core process.
- (b) Explain the sales and distribution module.
- (c) Explain marketing and sales in detail.
- (d) What is strategic planning? Explain the importance of strategic planning in a business enterprise.

Unit-III

- 3. (a) Explain EDP.
- (b) What is Decision Support System (DSS)? Explain its various attributes. What are the different types of Decision Support Systems.
- (c) Explain Executive Information System in detail.
- (d) What are the main misconceptions about ERP? What

[3]

are the limitations of ERP?

Unit-IV

4. (a) Define OLAP.
- (b) Explain MRP & MRP-II.
- (c) Explain major subsystems of manufacturing module.
- (d) Explain in detail the subsystems of finance.

Unit-V

5. (a) What are the ERP pre-implementation issues?
- (b) What is BPR? Explain the roles of BPR in implementing ERP?
- (c) Explain ERP implementation life cycle.
- (d) Describe in detail of project management in core business.

324833(24)

B. E. (Eighth Semester) Examination, 2020

APR-MAY

(New Scheme)

(Elect. Engg. Branch)

**INSTALLATION, MAINTENANCE & TESTING
of ELECTRICAL EQUIPMENTS**

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Part (a) of each question is compulsory and carries 2 marks. Attempt any two parts from (b), (c) and (d). Each of them carries 7 marks each.

Unit-I

1. (a) What do you mean by preventive and corrective maintenance?

2

- (b) Explain types and scope of maintenance. 7
- (c) Discuss recommended safety precautions against electric shocks in LV and HV installation. 7
- (d) What do you mean by safety management? Write down various principles of safety management. 7

Unit-II

- 2. (a) What parameters information are given on the transformer's name plate? 2
- (b) Write maintenance schedule of transformer upto 10000 kVA. 7
- (c) Explain the filtering process and filtering plant for transformer oil filtration with schematic diagram. 7
- (d) Write important steps in maintenance of power transformer and causes of failure. 7

Unit-III

- 3. (a) Define Type test, routine test and commissioning tests. 2

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- (b) Explain trouble shooting of substation equipments. 7
- (c) Write maintenance procedure of SF₆ circuit breaker. 7
- (d) Discuss troubles, causes and remedial action for outdoor circuit breaker in brief. 7

Unit-IV

- 4. (a) Why the test for degree of protection is necessary? 2
- (b) State the various steps in the installation and commissioning of induction motors. 7
- (c) Write drying out procedure of rotating electrical equipments. 7
- (d) Explain the mechanical maintenance of motor. 7

Unit-V

- 5. (a) What do you mean by hot line maintenance? 2
- (b) Explain various types of hot line operation. 7
- (c) Write safety procedures during hot line maintenance. 7
- (d) Explain Dry powder type fire extinguisher. 7

Printed Pages – 4

Roll No. :

324871(24)

APR-MAY

B. E. (Eighth Semester) Examination, 2020

(Old Scheme)

(Elect. & EEE Engg. Branch)

EHV AC & DC TRANSMISSION

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Attempt all questions. Part (a) is compulsory for each question. Attempt any two questions from part (b), (c) and (d).

Unit-I

1. (a) Enlist the limitation of HVDC transmission system.

(Any two)

2

[2]

- (b) Describe the operation of six-pulse GREATZ bridge circuit with detailed derivation. 7
- (c) Explain the modern trends of DC transmission technology. 7
- (d) Discuss the type of D.C. links used in DC transmission system. 7

Unit-II

2. (a) Define the term FACTS controller. 2
- (b) What is STATCOM? Explain its principle operation and draw the characteristics. 7
- (c) Describe the operation of TCR. 7
- (d) Explain the voltage profile along EHVAC line with light and heavy load. 7

Unit-III

3. (a) Define the term voltage instability. 2
- (b) An overhead conductor of 1.6 cm radius is 10 m

324871(24)

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- above the ground. The normal voltage is 133 kV (rms) to ground (230 kV) line to line. The switching surge experienced is 3.5 per unit. Taking $K = 0.7$, calculate the energy loss per km of line. Assume smooth conductors. 7
- (c) Explain the lighting phenomena in travelling waves. 7
- (d) Explain different protection system used against the overvoltage due to lighting. 7

Unit-IV

4. (a) What is the difference between even and odd harmonics. 2
- (b) What is smoothing reactor? Explain its functions to reduce harmonics in HVDC converters. 7
- (c) Explain converter station in HVDC transmission system. 7
- (d) Explain the designing of AC filters. 7

Unit-V

5. (a) Explain the term commutation failure? 2

324871(24)

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- (b) Describe the advantages and problems associated with EHVDC transmission system. 7
- (c) Explain HVDC converter firing angle control system. 7
- (d) Explain parallel operation of DC link with AC network. 7

Printed Pages – 6

Roll No. :

325833(25)

APR-MAY

B. E. (Eighth Semester) Examination, 2020

(New Scheme)

(EEE Engg. Branch)

COMPUTER AIDED POWER SYSTEM

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Attempt all questions. Part (a) of each question is compulsory. Attempt any two parts from (b), (c) and (d).

Unit-I

1. (a) Define Tree and Co-tree.

2

325833(25)

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- (b) Discuss the step by step method of formation of Y_{bus} 7
- (c) Explain in brief the procedure for formation of Y_{bus} using singular transformation. Derive the necessary equations. 7
- (d) An incomplete nodal admittance matrix for a 4-bus system with negligible charging admittance is given below. Find missing terms : 7

$$\begin{bmatrix} 0.7 - j_3 & -0.2 + j_1 & -0.5 + j_2 & y_{14} \\ y_{21} & y_{22} & -0.3 + j_2 & -0.5 + j_3 \\ y_{31} & y_{32} & y_{33} & -1 + j_4 \\ y_{41} & y_{42} & y_{43} & y_{44} \end{bmatrix}$$

Unit-II

2. (a) Why are fault studies important? 2
- (b) For the 3-bus network shown in fig. 1, find build Z_{bus} 7

[3]

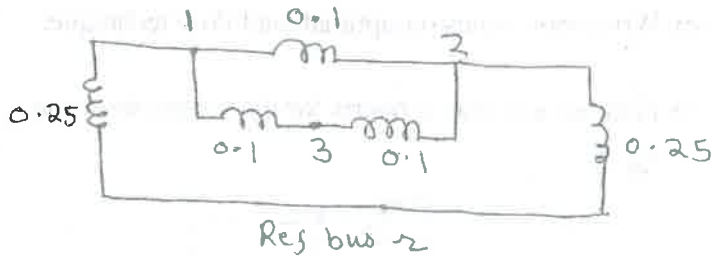


Fig. 1

(c) A generator experiences a double line to ground fault in phase b and c through a fault impedance Z_f . Derive the necessary expression for this fault and hence give the connection between three sequence networks. 7

(d) Why the phase shift in the positive sequence and negative sequence quantities through a star delta transformer are opposite to each other? Explain in brief. 7

Unit-III

3. (a) What is meant by optimal load flow? 2

(b) Draw and explain flow chart for fast decoupled load flow method. 7

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(c) Write short notes on optimal load flow technique. 7

(d) Find bus admittance matrix for the system shown in fig. 2. 7

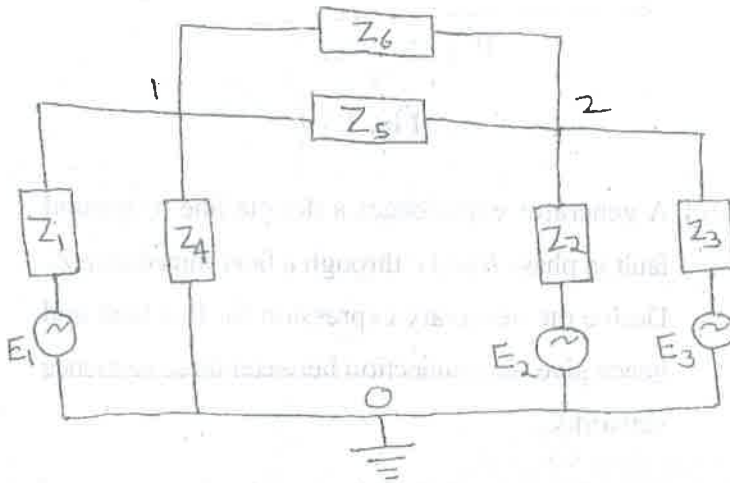


Fig. 2

Unit-IV

4. (a) What is the essential difference between steady state stability and transient stability? 2

(b) Write down the swing equation and drive the expression for iterative solution of swing equation using modified Euler method. 7

[5]

- (c) How can the transient stability of a system be improved?
Discuss the traditional as well as new approaches to the problem. 7
- (d) A 50 Hz, 4 pole turbogenerator rated 100 mVA, 11 kV has an inertia constant of 0.8 MJ/mVA :
- (i) Find the stored energy in the rotar at synchronous speed.
 - (ii) If the mechanical input is suddenly raised to 80 MW for an electrical load of 50 MW, find rotar acceleration, neglecting mechanical and electrical losses.
 - (iii) If the acceleration calculated in part (ii) is maintained for 10 cycles. Find the change in torque angle and rotar speed in revolution per minute at the end of this period. 1+3+3=7

Unit-V

5. (a) What is contingency analysis? 2
- (b) Discuss the factors affecting power system security. 7
- (c) Explain AC power flow method of contingency analysis. 7

(d) Explain following terms : (any two) 7

- (i) Contingency selection
- (ii) Network sensitivity method for contingency analysis
- (iii) Static security analysis at control centers

327833(27)

B. E. (Eighth Semester) Examination, 2020

APR-MAY

(New Scheme)

(EI Branch)

INDUSTRIAL ELECTRONICS

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Attempt all questions. Part (a) of each question is compulsory. Attempt any two parts from (b), (c) and (d). Sketch neat and clear diagram and waveform wherever necessary.

Unit-I

1. (a) What do you mean by controlled rectifiers? 2

- (b) Explain the principle of operation of single phase, half-wave controlled converted with R-load. Draw the waveforms for (a) output average voltage across the load (b) average current (c) voltage across SCR. 7
- (c) A half-wave controlled rectifier circuit is connected to a purely resistive load. Find out the maximum value of the resistance to be connected as a load when $\alpha_{\min} = 10^\circ$. The latching and holding current for thyristor are 10 mA and 5 mA respectively. The circuit is operated from $V = 100 \sin 314 t$. Find out the angle of thyristor. 7
- (d) Write a short note on ideal and practical dual converters. 7

Unit-II

2. (a) What is Cycloconverter? 2
- (b) An AC voltage controller has a resistive load of $R = 10 \Omega$ and RMS input voltage is $V_s = 230 \text{ V}$, 50 Hz. The SCRs are switched on for $n = 25$ cycles and off for $m = 75$ cycles.

Determine :

- (i) RMS output voltage
- (ii) Input power factor
- (iii) Average and RMS rating of SCRs 7
- (c) Describe the operation of single phase to single phase cycloconverter for an inductive load. 7
- (d) Write the single phase voltage controller working principle with proper circuit diagram. 7

Unit-III

- 3. (a) List a few industrial application in inverters. 2
- (b) Explain the various methods of reduction of harmonics from output voltage of inverter. 7
- (c) Describe the working of a single phase parallel inverter with relevant circuit and waveforms. 7
- (d) Write a short notes on series inverters. 7

Unit-IV

- 4. (a) What is SMPS? 2

- (b) What is an UPS? Give its industrial application.
Describe rotating-type UPS configuration. 7
- (c) What is a static switch? List the merits of static
switch over mechanical switches. 7
- (d) What are solid state relays? How is electrical isolation
obtained in these relays? 7

Unit-V

- 5. (a) What is thermal times? 2
- (b) Explain principle of induction heating. Enlist merits
of induction heating over conventional method. 7
- (c) Explain the basic principle of high-frequency
dielectric heating. Give two applications. 7
- (d) Classify timers according to the functions and techniques. 7

328811(28)

APR-MAY

B. E. (Eighth Semester) Examination, 2020

(Old Scheme)

(Et & T Engg. Branch)

OPTICAL COMMUNICATION

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Attempt all questions. Part (a) from each question is compulsory. Attempt any two parts from (b), (c) and (d) of each question.

Unit-I

1. (a) Define Snell's law of refraction. 2
- (b) What is step-index fiber? Explain the refractive index profile and ray transmission in step index fiber. 7

[2]

- (c) Explain different types of attenuation in an optical fiber. 7
- (d) A silica optical fiber has a core refractive index of 1.50 and a cladding refractive index of 1.47. Determine (i) The critical angle at the core cladding interface (ii) The NA for the fiber (iii) The acceptance angle in air for the fiber. 7

Unit-II

2. (a) What are the advantages of LED source? 2
- (b) Explain edge emitter LEDs structure in detail. 7
- (c) What is meant by population inversion? Explain its significance. 7
- (d) A DH surface emitter which has an emission area diameter of $50 \mu\text{m}$ is butt joint to an $80 \mu\text{m}$ core step index fiber with a NA of 0.15. The device has a radiance of $30 \text{ W Sr}^{-1} \text{ cm}^{-2}$ at a constant operating drive current. Estimate the optical power coupled into the fiber if it is assumed that the Fresnel reflection coefficient at the index matched fiber surface is 0.01. 7

328811(28)

[3]

Unit-III

3. (a) Explain the significance of fiber coupler. 2
- (b) Write short note on mechanical splices. 7
- (c) Explain star coupler in detail. 7
- (d) Write short note on distribution network. 7

Unit-IV

4. (a) What is the function of optical detector? 2
- (b) Explain the principle of photo-detection. 7
- (c) Explain the construction and working of PIN Photo diode. 7
- (d) When 3×10^{11} photons each with a wavelength of $0.85 \mu\text{m}$ are incident on a photo diode, on average 1.2×10^{11} electrons are collected at the terminals of the device. Determine the quantum efficiency and the responsibility of the photo diode at $0.85 \mu\text{m}$. 7

Unit-V

5. (a) What is optical network? 2

328811(28)

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[4]

- (b) Explain cut-back technique for the measurement of spectral loss in optical fiber. 7
- (c) Explain the measurement technique for intermodal dispersion. 7
- (d) Write short notes on SONET. 7

328812(28)

B. E. (Eight Semester) Examination, 2020

(Old Scheme)

(Et & T Engg. Branch)

VLSI DESIGN

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Part (a) of each question is compulsory.

Attempt any two parts from (b), (c) and (d).

Unit-I

1. (a) Define CPLD. 2
- (b) What are differences in SSI, MSI and LSI? 7

[2]

- (c) Explain VLSI Design flow chart with diagram. 7
- (d) Explain FPGA architecture with block diagram. 7

Unit-II

- 2. (a) Define Bi-CMOS. 2
- (b) Explain PMOS fabrication process. 7
- (c) What are the main point of Lambda based design rule? Explain it. 7
- (d) Draw schematic and stick diagram for 2 input CMOS NOR Gate. 7

Unit-III

- 3. (a) Define Layout. 2
- (b) Draw and explain 4×4 NAND-ROM layouts. 7
- (c) Draw and explain layout of JK flip flop. 7
- (d) Construct layout for 1 bit full adder. 7

Unit-IV

[3]

- 4. (a) Define VHDL. 2
- (b) Explain the static and dynamic power dissipation in CMOS inverter. 7
- (c) Explain different type Architecture body in VHDL. 7
- (d) What is entity in VHDL? Explain the entity declaration. 7

Unit-V

- 5. (a) Define "process" in VHDL. 2
- (b) Write VHDL code for D-flip flops. 7
- (c) Explain inertial delay model and transport delay model in VHDL. 7
- (d) Write the comparison of Moore and Mealy FSM. 7

Printed Pages – 4

Roll No.

328813(28)

APR-MAY

B. E. (Eighth Semester) Examination, 2020

(Old Scheme)

(E & T Branch)

INDUSTRIAL & POWER ELECTRONICS

Time Allowed: Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : All questions are compulsory. Part (a) is compulsory and solve any two from parts (b), (c) and (d).

Unit-I

1. (a) What is the Breakdown mechanism of Zener diode. 2

(b) Explain three terminal voltage regulator using LM-340IC.

328813(28)

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[2]

- (c) Explain basic transistorized shunt voltage Regulator and how its performance can be improved? 7
- (d) Write short notes on : (any **one**) 7
- (i) SMPS
- (ii) Dual Tracking Regulator

Unit-II

2. (a) Justify the statement "Higher is the gate current, lower is the fwd breakover voltage". 2
- (b) Give the comparison between any three thyristor family members. 7
- (c) What is the basic difference between load commutation and external pulse commutation? 7
- (d) Write short notes on :
- (i) Different methods of triggering SCR circuits 4
- (ii) SCR's operation - series & parallel operation 3

Unit-III

3. (a) What do you mean by Chopper & write used. 2

[3]

- (b) Explain the working principle of three phase converter. 7
- (c) Explain the single mid-point cycloconverter with the help of circuit. 7
- (d) Describe McMurray bridge inverter in brief. 7

Unit-IV

4. (a) Define skin effect in Induction Heating. 2
- (b) Explain different types of Resistance Welding. 7
- (c) Write the limitations, theory and effect of variation of supply voltage & frequency of "dielectric heating" with two application. 7
- (d) For the high frequency induction heating derive the total power entering the metal per sq. cm. of the surface given by : 7

$$P_t = \frac{8\pi H_0 \sqrt{10^{-9} \mu_r f}}{\sqrt{\sigma}}$$

Unit-V

5. (a) Explain origin of noise. 2
- (b) Briefly with the help of B.D. of operation of ONLINE UPS and OFFLINE UPS. 7
- (c) What are the different types of noise? Explain any three in brief. 7
- (d) Write short notes on : (any one) 7
- (i) Servo Motor of servo system
 - (ii) Buck-Boost control voltage stabilizer

328831(28)

APR-MAY

B. E. (Eighth Semester) Examination, 2020

(New Scheme)

(Et & T Engg. Branch)

ADVANCED COMMUNICATION SYSTEMS

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Part (a) of each question is compulsory.

Attempt any two parts from (b), (c) and (d)

Unit-I

1. (a) What is Satellite Stabilization? 2
- (b) A geo-synchronous satellite moving in a equatorial circular orbit at the height 35786 k.m. from the earth

[2]

surface. If the earth radius is taken as 6378 km. Determine the coverage angle and slant range (elevation angle = 0°). 7

(c) What are the elements of satellite communication system? Explain each with suitable block diagram. 7

(d) Explain the basic differences between an active satellite systems. Discuss their merit and demerits. 7

Unit-II

2. (a) Define Noise figure and Noise temperature. 2

(b) Why satellite link design is done? Derive the general link design equation for communication satellite. 7

(c) Explain in detail interference effects on complete link design. 7

(d) In the link budget of a satellite, the free space loss at 12 GHz is 210 db, the antenna pointing loss is 2 db and atmospheric absorption is 2 db. If the receiver C/T ratio is 19 db/K, receiver feeder losses are 1 db 8 the E&RP is 50 dbW. Calculate the carrier to noise spectral density ratio. 7

Unit-III

328831(28)

3. (a) What is difference between multiplexing and multiple access technique? 2
- (b) What is Burst? Explain the difference between the burst and traffic burst. Explain their structure too. 7
- (c) What is CDMA? Explain in detail. In what way it is superior to TDMA. 7
- (d) Explain the operation of typical satellite switched TDMA (SSTDMA) system. 7

Unit-IV

4. (a) Define skew rays. 2
- (b) A multimode step index fiber has a numerical aperture of 0.3 and core refractive index of 1.45. The material dispersion parameter for the fibre is $250 \text{ PS nm}^{-1} \text{ km}^{-1}$ which makes material dispersion the totally dominating intrumodal dispersion mechanism. Estimate :
- (i) Total rms pulse broadening per km when the fiber is used with an LED source of rms spectral width 50 nm.
- (ii) Corresponding bandwidth length product for the fiber. 7

- (c) Explain different types of attenuations used in optical fiber communication. 7
- (d) Explain with the aid or diagram :
- (i) The multimode step index fiber
 - (ii) The single mode step index fiber.
- Compare the advantages and disadvantages of these two types of fiber for use as an optical channel. 7

Unit-V

5. (a) Define homojunction and hetrojunction LED. 2
- (b) Compare the LED of LASER on the following points :
- (i) Spectral width
 - (ii) Coupling efficiency
 - (iii) Modulation B.W.
 - (iv) Lifetime
 - (v) Cost
 - (vi) Temp. sensitivity
 - (vii) Compatible fiber 7
- (c) Compare SONET & SDH optical network. 7

[5]

(d) Write short note on any **two** :

7

- (i) Semiconductor photodiode
- (ii) PIN photodiode
- (iii) Avalanche photodiode

328833(28)

B. E. (Eighth Semester) Examination, 2020
APR-MAY
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(New Scheme)

(ET & T Engg. Branch)

POWER ELECTRONICS

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Attempt all questions. Part (a) of each question is compulsory. Attempt any two parts from (b), (c) and (d). Draw neat sketch & waveforms with proper labelling wherever required.

Unit-I

1. (a) Compare GTO & SCS. 2

- (b) With help of proper sketch, explain Mesa type construction of SCR. What are its advantages. 7
- (c) Explain two transistor analogy of SCR. Derive the expression of anode current in two transistor analogy. What is the condition of conducting SCR. 7
- (d) What is the difference between Symmetric & Asymmetric IGBT. Explain the working of Asymmetric IGBT. 7

Unit-II

2. (a) Compare natural commutation & forced commutation. 2
- (b) What is the need of series & parallel operation of SCR. Discuss the importance of series equalization circuit in static condition & find out the value of resistance connected across each SCR. 7
- (c) With help of neat waveforms, explain dynamic turn on & turn off switching characteristics of SCR. 7
- (d) With help of neat sketch & waveforms, explain the working of single phase full wave converter using RLE load. 7

Unit-III

3. (a) Differentiate between Symmetric & Asymmetric semiconverter. 2
- (b) With help of neat sketch & waveforms, explain three phase fully controlled Bridge convertor for firing angle 30° & 90° . 7
- (c) A half controlled Bridge converter feeds a load with ripple free current $\alpha = 60^\circ$, input voltage is 240 V, 50 Hz, $R_L = 10\Omega$. 7
- Find :
- (i) Average load voltage
- (ii) Average Power dissipated in load
- (iii) RMS input current
- (d) Difference between circulating current type & non circulating current type modes of Dual converter. Explain how single phase dual converter works in all four quadrants. 7

Unit-IV

4. (a) Define constant frequency mode & variable frequency mode of chopper. 2

- (b) With help of neat sketch & waveforms. Explain single phase full bridge inverter using R (Resistive) load. 7
- (c) With help of neat sketch & waveforms, explain working of Jone's chopper. 7
- (d) With help of neat sketch & waveforms and explain working of 3 phase bridge inverter using 180° conduction mode. 7

Unit-V

5. (a) What is step down cycloconverter. 2
- (b) Explain the TRIAC based AC voltage controller. 7
- (c) With help of circuit diagram & waveforms explain working of three phase to single phase cycloconverter. 7
- (d) Write short notes on following : 7
- (i) Integral cycle control in AC voltage controller.
 - (ii) Single phase to single phase cycloconverter using bridge configuration.

328840(28)

B. E. (Eighth Semester) Examination, 2020
APR-MAY
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(New Scheme)

(ET&T Engg. Branch)

CRYPTOGRAPHY & SECURE COMMUNICATION

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Attempt all questions. Part (a) of each question is compulsory carrying 2 marks. Attempt any two parts from parts (b), (c) and (d) carrying 7 marks each.

Unit-I

1. (a) Define finite group and order of group.

- (b) Explain Euler's theorem with example.
- (c) Write Euclidean algorithm to obtain the greatest common divisor and extended Euclidean algorithm to obtain the multiplicative inverse with example.
- (d) State and explain Fermat's theorem with example.

Unit-II

- 2. (a) Define Block cipher and Stream Cipher.
- (b) Briefly describe the working of Data Encryption Standard (DES).
- (c) Explain RSA algorithm with example in detail along with its advantages and disadvantages.
- (d) Explain Diffie-Hellman key exchange algorithm and show how this algorithm is insecure against a Man-in-the-middle attack.

Unit-III

- 3. (a) Define Hash function.

[3]

- (b) Briefly describe the MD5 algorithm with the working steps in it.
- (c) Explain Digital signature with its advantages and disadvantages.
- (d) Describe the basic usage of Message Authentication Code (MAC).

Unit-IV

- 4. (a) Define Virus and Firewall.
- (b) Explain the services provided by IPSec in detail.
- (c) Mention, how the most significant types of viruses can be categorized.
- (d) Describe firewall configurations in brief.

Unit-V

- 5. (a) What is the purpose of dual signature?
- (b) Briefly describe the overall operation of SSL Record protocol with SSL Record format.

[4]

- (c) Draw a table of comparison of threats, their consequences and counter measures.
- (d) What is Secure Electronic Transaction (SET)? Give an overview of SET along with its key features.

328844(28)

APR-MAY

B. E. (Eighth Semester) Examination, 2020

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(New Scheme)

(Et&T Engg. Branch)

**MICROELECTRONIC DEVICES
& VLSI TECHNOLOGY**

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Part (a) of each question is compulsory having 2 marks each and attempt any two parts from (b), (c) and (d) from each question having 7 marks each.

Unit-I

1. (a) What is Moore's Law?

2

[2]

- (b) Explain the Czochralski (CZ) technique of crystal growth. Why it is preferred over other techniques? 7
- (c) Write detail history of evolution in Integrated circuit. 7
- (d) Explain the Bridgeman technique. 7

Unit-II

- 2. (a) Why oxidation is needed in Integrated circuit? 2
- (b) Explain Thermal Oxidation. Write the difference between thick & thin oxidation. 7
- (c) Explain kinetics of thermal oxidation. 7
- (d) Explain the purpose of film deposition. Also explain polysilicon deposition. 7

Unit-III

- 3. (a) Define Diffusion. What are the type of dopents give examples? 2
- (b) Explain Ion Impantation with suitable diagram. 7

- (c) Compare low energy & high energy implantation. 7
- (d) Explain Diffusion equation & Diffusion mechanism. 7

Unit-IV

4. (a) Why Metallization is needed? 2
- (b) What is Lithography? Explain the electron beam Lithography. 7
- (c) What is Epitaxy? Explain the molecular beam Epitaxy. 7
- (d) Write short notes on : 7
- (i) Dry etching vs Wet etching
 - (ii) Process simulation and integration

Unit-V

5. (a) What are the types of MOSFET? 2
- (b) Explain the MOS capacitance with equivalent circuit. 7
- (c) Explain the scaling of MOSFET. Also mention its benefits. 7

(d) Write short notes on : 7

(i) Channel length modulation

(ii) Sub-Threshold Region

328845(28)

APR-MAY

B. E. (Eighth Semester) Examination, 2020

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(New Scheme)

(Electronics & Telecommunication Engg. Branch)

BIOMETRIC TECHNIQUES

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Attempt all questions. Part (a) of each unit is compulsory and carries 2 marks. Attempt any two parts from (b), (c) and (d), each carry 7 marks. Assume suitable data if required.

Unit-I

1. (a) How is identification different from verification? 2
- (b) How do we evaluate the performance of biometric

system? What are various causes of errors in the biometrics? 7

(c) Define template. How do we use the templates in biometric recognition? 7

(d) Explain the basic process involved in biometrics verification and identification. 7

Unit-II

2. (a) Define self similarity in an image. 2

(b) Discuss EIGEN face method of face recognition system. 7

(c) What are the steps required to design an iris recognition system? 7

(d) What are the various advantages and disadvantages of iris biometrics? 7

Unit-III

3. (a) Define ridge, valleys and minute. 2

(b) What are the main stages of pre-processing involved in fingerprint matching? 7

[3]

- (c) Why is SIFT algorithm most widely used for feature extraction? Draw and explain various stages involved in ISL recognition system. 7
- (d) Fingerprint biometrics is now commonly used at attendance record systems. What are the advantages and disadvantages of this application? 7

Unit-IV

4. (a) Define biometric cryptography. 2
- (b) Explain public key cryptography. Discuss secrecy and authenticity. 7
- (c) Discuss DES algorithm in detail. 7
- (d) Discuss RSA algorithm and compare it with DES algorithm. 7

Unit-V

5. (a) What do you mean by biometric standards? 2
- (b) How does AADHAAR help in providing various services to the common people? Explain. 7

- (c) What are the challenges of single modality biometrics and how does multimodal biometric system overcome them? 7
- (d) Discuss DNA biometric system. 7

Printed Pages – 3

Roll No. :

328847(28)

B. E. (Eighth Semester) Examination, 2020

APR-MAY

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(New Scheme)

(ET&T Branch)

ARTIFICIAL INTELLIGENCE & EXPERT SYSTEM

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Attempt all questions. Part (a) is compulsory from each unit and solve any two out of (b), (c) and (d). Assume suitable data if required.

Unit-I

1. (a) Explain any two characteristics of AI. 2

328847(28)

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[2]

- (b) Explain BFS and DFS technique with suitable example. 7
- (c) Explain applications of AI in different fields 7
- (d) What is forward and backward chaining? 7

Unit-II

- 2. (a) What is heuristic search technique? 2
- (b) What is hill climbing & what are the problems in hill climbing? 7
- (c) Explain A* algorithm with suitable example. 7
- (d) Explain alpha-beta cut off with suitable example. 7

Unit-III

- 3. (a) What is knowledge representation? 2
- (b) Discuss the resolution in predicate logic. 7
- (c) What is Semantic Network? 7
- (d) What is Conceptual Dependency? 7

[3]

Unit-IV

4. (a) What is natural language processing? 2
(b) Explain RTN and ATN with suitable example. 7
(c) What is Block Word? Explain with suitable example. 7
(d) Explain Bayesian network with example. 7

Unit-V

5. (a) What is Expert System? 2
(b) Explain architecture of expert system. 7
(c) What is knowledge acquisition? 7
(d) How AI used in MYCIN? 7

Printed Pages – 4

Roll No. :

328848(28)

B. E. (Eighth Semester) Examination, 2020

APR-MAY

(New Scheme)

(Et. & T Engg. Branch)

**TELECOMMUNICATION SWITCHING CIRCUITS
and NETWORKS**

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : All questions are compulsory. Part (a) is compulsory and from remaining you have to attempt any two parts (b), (c) & (d) of each question. The figures in the right hand margin indicate marks.

Unit-I

1. (a) What do you mean by folded and non-folded network?

2

- (b) Discuss basic elements of switching system. 7
- (c) Explain the principle of switching and its switch configuration with neat sketch. 7
- (d) What is centralised SPC? Explain its working with different modes of configuration. 7

Unit-II

2. (a) What do you understand by Digital Switching System? 2
- (b) Explain time division space switching with suitable diagram. 7
- (c) Explain software architecture of call processing in briefly. 7
- (d) Discuss the various electronic exchanges in India. 7

Unit-III

3. (a) What is GOS of a delay system? 2
- (b) Explain Birth-Death process with its probabilities. 7
- (c) How to work in echo suppressors in transmission plan? 7

- (d) What is the basic difference between in-channel signalling and common channel signalling? 7

Unit-IV

4. (a) Explain to data networks are classified according to geographical coverage. 7
- (b) Discuss various switching techniques for data transmission in PSTN. 7
- (c) Explain the role and importance of end-to-end layers in data communication architecture. 7
- (d) Calculate the through put of pure ALOHA and slotted ALOHA in satellite based data network (SBDN). 7

Unit-V

5. (a) What do you mean by ISDN? 2
- (b) What are various new service supported by ISDN? Give a brief description of few services. 7
- (c) Explain network and protocol architecture of ISDN. 7

(d) Explain user level signalling and network level signalling in detail.

328872(28)

APR-MAY

B. E. (Eighth Semester) Examination, 2020

(Old Scheme)

(ET & T Engg. Branch)

RADAR ENGINEERING and NAVIGATIONAL AIDS

Time Allowed : Three hours

Maximum Marks : 80

Minimum Pass Marks : 28

Note : Attempt all questions. Part (a) of each question is compulsory and carries 2 marks and attempt two parts from (b), (c) and (d) and carry 7 marks each.

Unit-I

1. (a) What is RADAR? 2
- (b) Derive the expression for RADAR range equation and give its application. 7

[2]

- (c) Discuss the limitation to the backing accuracy of Radar. 7
- (d) Draw the basic block diagram of pulse RADAR and explain the various block in brief. 7

Unit-II

2. (a) Define Doppler effects. 2
- (b) Draw the block diagram of MTI Radar. Explain the functioning of each block alongwith delay line canceller. 7
- (c) Write a short notes on : 7
- (i) Conical Scan
- (ii) Law Angle Tracking
- (d) Draw the block diagram of sequential lobing trucker radar and explain its operation. 7

Unit-III

3. (a) What is refraction and diffraction of radar wave? 2
- (b) What are the various external noise limit the detedability of radar tanget. 7

328872(28)

[3]

- (c) Write short notes on the terms : 7
- (i) Refraction
- (ii) Scattering
- (iii) Diffraction
- (d) Describe forward scattering from flat candle. 7

Unit-IV

4. (a) What are the various function performed by antenna? 2
- (b) Write short notes on cosecant squared antenna. 7
- (c) Explain the various types of parabolic reflector. 7
- (d) Write short notes on Radome. 7

Unit-V

5. (a) Define Noise figure. 2
- (b) Draw and explain the block diagram of super hetrodyne receiver. 7
- (c) Explain different types of Radar display. 7

328872(28)

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(d) Write short notes on :

7

(i) Magnetron

(ii) ECM

328875(28)**B. E. (Eight Semester) Examination,
April-May 2020****(Old Scheme)****(Et & T Engg. Branch)****MICRO-ELECTRONIC DEVICES & VLSI
TECHNOLOGY****(Elective-III)*****Time Allowed : Three hours******Maximum Marks : 80******Minimum Pass Marks : 28***

Note : All questions carry equal marks. Part (a) of each question is compulsory. Attempt any two from (b), (c) & (d).

Unit-I

1. (a) What do you mean by scale of Integration. Give the classification. 2

328875(28)**PTO**

- (b) Why CZ techniques is preferred over the other techniques in silicon processing. 7
- (c) Give comparative analysis of Bridgeman Technique and Float Zone process. 7
- (d) Explain the process of silicon wafer preparation. 7

Unit-II

2. (a) Give the types of Oxidation process. 2
- (b) Show that to grow an oxide layer of thickness x , a thickness of $0.44 x$ of silicon is consumed. 7
- (c) Explain Dielectric Deposition with neat diagram. 7
- (d) Explain Polysilicon Deposition in detail. 7

Unit-III

3. (a) Define the Fick's diffusion law. 2
- (b) Draw & explain the ion implantation system. Also explain the role of mass separator & Beam scanning in detail. 7

328875(28)

[3]

- (c) Which implantation techniques avoids long diffusion steps. Explain the terms implantation damage, channeling & recoils. 7
- (d) Explain Vacancy mechanism & Interstitial mechanism. 7

Unit-IV

4. (a) Define EPITAXY & give its uses in MOS structure. 2
- (b) (i) Explain optical Lithography with neat diagram. 5
- (ii) A proximity printer operates with a 20 μ m marks of wafer gap and a wavelength of 250 nm. Find line width that can be obtained. 2
- (c) Give comparison between WET & DRY ETCHING. 7
- (d) Explain the flow diagram of process simulation and Integration. 7

Unit-V

[4]

5. (a) Draw MOSFET structure. 2
- (b) Explain the operation of *N* channel MOSFET with pictorial view. 7
- (c) Explain following :
- (i) Channel Length Modulation 3½
- (ii) Subthreshold Region 3½
- (d) Explain scaling of MOSFET. 7